



ENVIRONMENTAL AND PACKAGE TESTING DATA FOR DPAK (TO-252)					
STRESS	SAMPLE SIZE	DEVICE HR./CYC	CONDITION	TOTAL FAILS	FAIL PERCENTAGE
BOND INT	2040	1 030 000	200 °C + N2	0	0.00
HAST	6806	680 600	130 °C, 85 % RH	0	0.00
Power Cycle	5740	80 949 908	DELTA T _J = 100 °C	0	0.00
Pressure Pot	6906	662 976	121°, 15 PSIG	0	0.00
Solder DUNK	3850	11 550	260 °C, 10 s	0	0.00
Solderability	1020	8160	883 M2003	0	0.00
Temp. Cycle	6924	6 964 380	-55 °C to 150 °C	0	0.00